# PRODUCT / PROCESS CHANGE NOTIFICATION

| 1. PCN basic data | |
|---|---|
| 1.1 Company | STMicroelectronics International N.V |
| 1.2 PCN No. | POWER AND DISCRETES/26/16565 |
| 1.3 Title of PCN | DPC ACA Wafer AOI Machine Qualification. |
| 1.4 Product Category | Pls Refer to the impacted Products List |
| 1.5 Issue date | 2026-09-01 |

| 2. PCN Team | |
|---|---|
| 2.1 Contact supplier | |
| 2.1.1 Name | PIKE EMMA |
| 2.1.2 Phone | +44 1628896111 |
| 2.1.3 Email | emma.pike@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Angelo RAO |
| 2.1.2 Marketing Manager | Francesco FISICHELLA |
| 2.1.3 Quality Manager | Massimiliano CUOZZO |

| 3. Change | | |
|---|---|---|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Methods | Process flow chart: Revision change in Process like addition, deletion of process step | SH1A---ST SHENZHEN -CHINA |

| 4. Description of change | | |
|---|---|---|
| | Old | New |
| 4.1 Description | DSC TMM line product AVI is performed on M KGD Camtek.<br>H2PAK line product does not deploy post-saw AVI | AVI for DSC TMM and H2PAK products is performed on E3 DPC |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | Processability | |

| 5. Reason / motivation for change | |
|---|---|
| 5.1 Motivation | - E3 DPC does not have an AVI machine for sawn wafer inspection, and some products require post-saw AVI.<br>- Current AVI was performed on M KGD Camtek. |
| 5.2 Customer Benefit | CAPACITY INCREASE |

| 6. Marking of parts / traceability of change | |
|---|---|
| 6.1 Description | By internal traceability |

| 7. Timing / schedule | |
|---|---|
| 7.1 Date of qualification results | 2026-08-17 |
| 7.2 Intended start of delivery | 2027-02-13 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|---|---|---|---|
| 8.1 Description | 16565 ACA Wafer AOI Qualification Report for PCN.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2026-09-01 |

| 9. Attachments (additional documentations) |
|---|
| 16565 Public product.pdf<br>16565 ACA Wafer AOI Qualification Report for PCN.pdf |

| 10. Affected parts | | |
|---|---|---|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | SCT040H120G3AG | |
| | SCT070H120G3AG | |

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